



Material Composition Declaration

EPC2034C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/6/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	18.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	13.8376	74.5992	77.6279	745992
	Silicon oxide	7631-86-9	0.0692	0.3731		3731
	Silicon nitride	12033-89-5	0.0246	0.1325		1325
	Gallium nitride	25617-97-4	0.1226	0.6610		6610
	Aluminum	7429-90-5	0.1439	0.7759		7759
	Aluminum nitride	24304-00-5	0.0274	0.1478		1478
	Titanium	7440-32-6	0.0037	0.0198		198
	Titanium nitride	25583-20-4	0.0190	0.1023		1023
	Copper	7440-50-8	0.0024	0.0129		129
	Tungsten	7440-33-7	0.0025	0.0133		133
Under Bump Metal	Polyimide		0.1465	0.7898	0.7728	7898
	Titanium	7440-32-6	0.0017	0.0091		91
	Copper	7440-50-8	0.1417	0.7637		7637
Solder Bump	Tin	7440-31-5	3.8262	20.6273	21.5993	206273
	Silver	7440-22-4	0.1603	0.8640		8640
	Copper	7440-50-8	0.0200	0.1080		1080
Sum in total:			18.5493	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.